

SOT310-1

plastic quad flat package; 80 leads (lead length 1.6 mm);
body 14 x 20 x 3.0 mm

8 February 2016

Package information

1. Package summary

Terminal position code	Q (quad)
Package type descriptive code	QFP80
Package type industry code	QFP80
Package style descriptive code	QFP (quad flat package)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
IEC package outline code	112E08
JEDEC package outline code	MS-022
Mounting method type	S (surface mount)
Issue date	25-2-2003

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	19.9	-	20	20.1	mm
E	package width	13.9	-	14	14.1	mm
A	seated height	[tbd]	-	3.4	3.4	mm
A ₂	package height	2.8	-	3	3.2	mm
n ₂	actual quantity of termination	-	-	80	-	

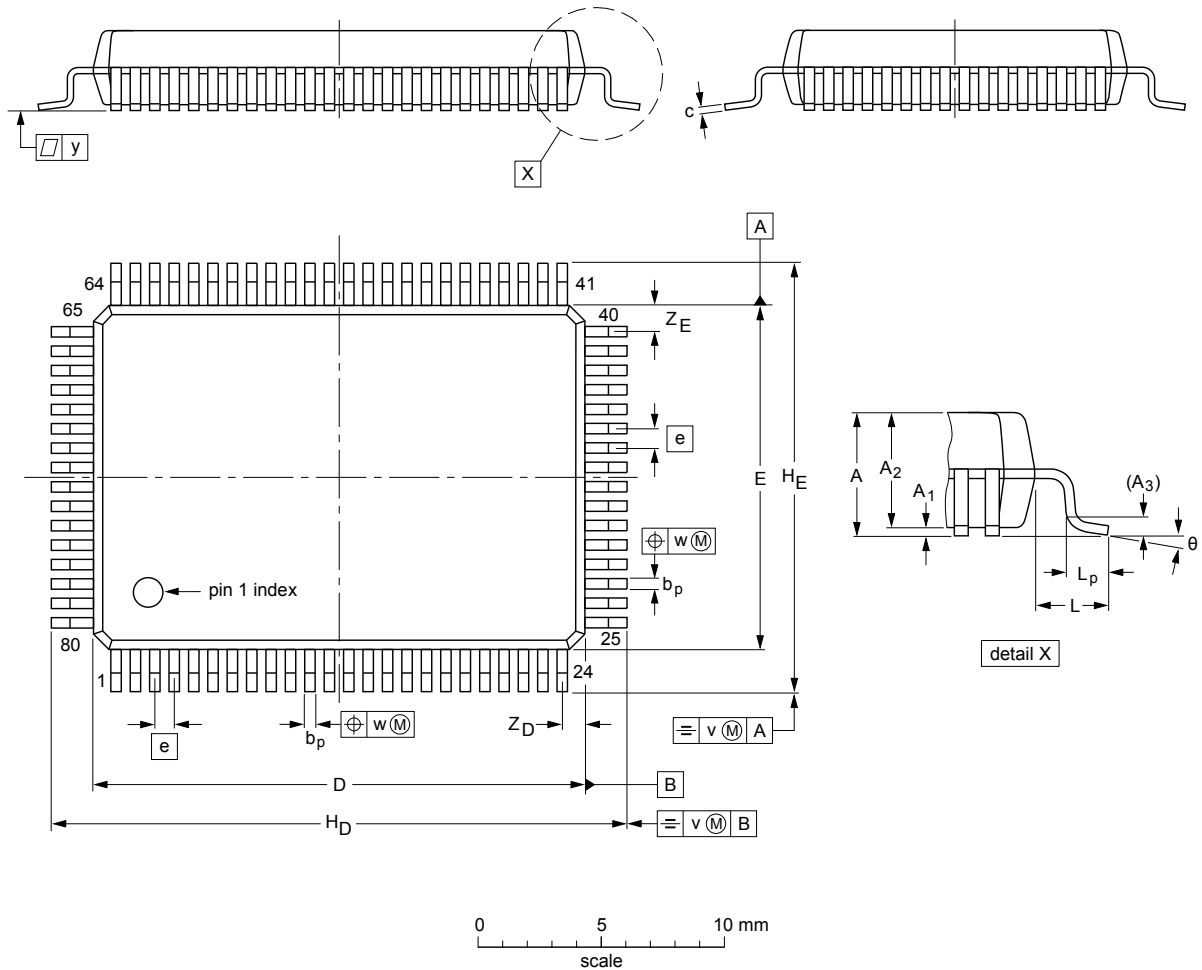


plastic quad flat package; 80 leads (lead length 1.6 mm); body 14 x 20 x 3.0 mm

2. Package outline

QFP80: plastic quad flat package; 80 leads (lead length 1.6 mm); body 14 x 20 x 3 mm

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DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A ₁	A ₂	A ₃	b _p	c	D ⁽¹⁾	E ⁽¹⁾	e	H _D	H _E	L	L _p	v	w	y	Z _D ⁽¹⁾	Z _E ⁽¹⁾	θ
mm	3.4	0.2 0	3.2 2.8	0.25	0.45 0.30	0.25 0.14	20.1 19.9	14.1 13.9	0.8	23.6 22.8	17.6 16.8	1.6	1.1 0.5	0.3	0.15	0.1	1.0 0.6	1.2 0.8	7° 0°

Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT310-1	134E14	MS-022				00-01-19 03-02-25

Fig. 1. Package outline QFP80 (SOT310-1)

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3. Soldering

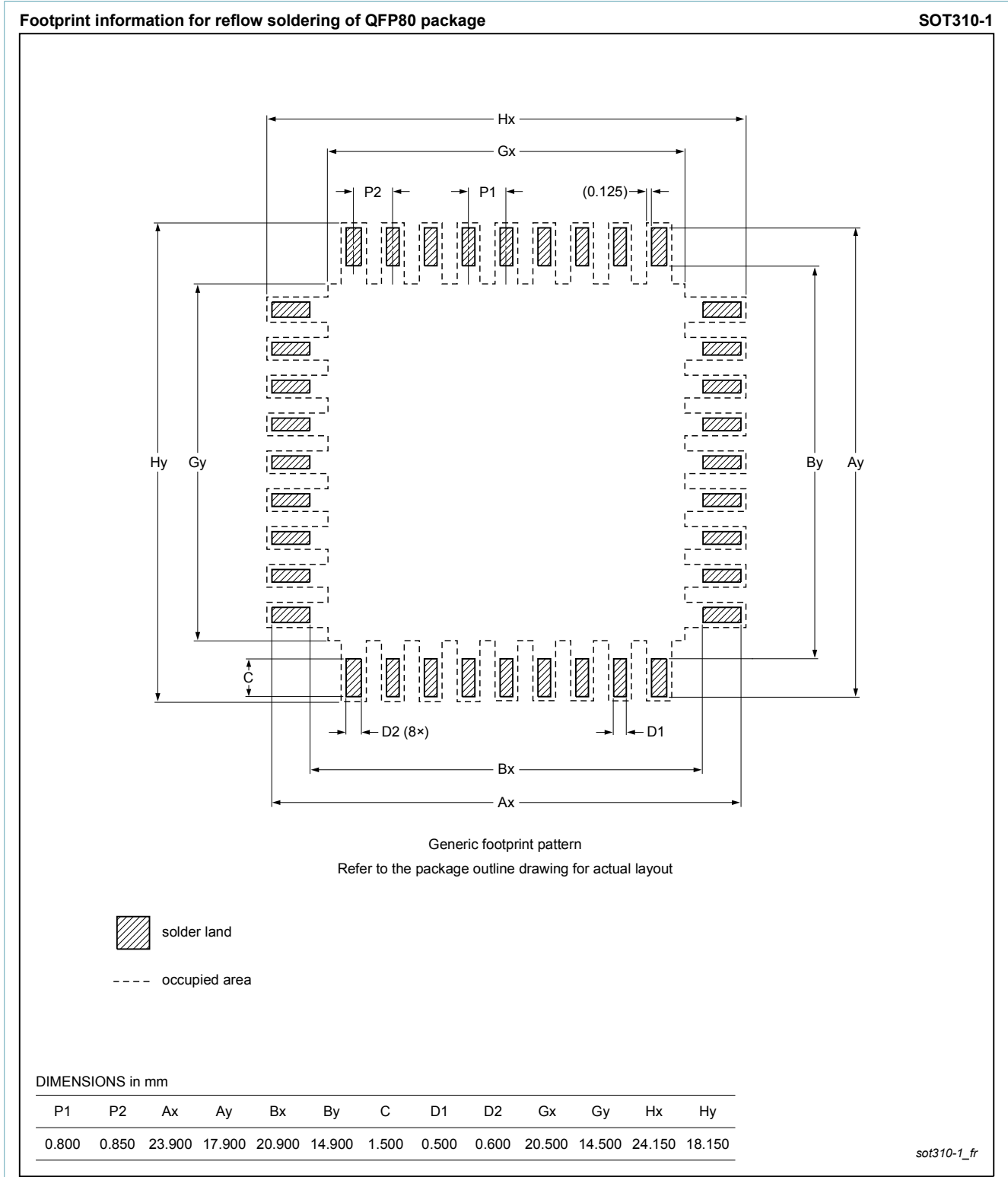
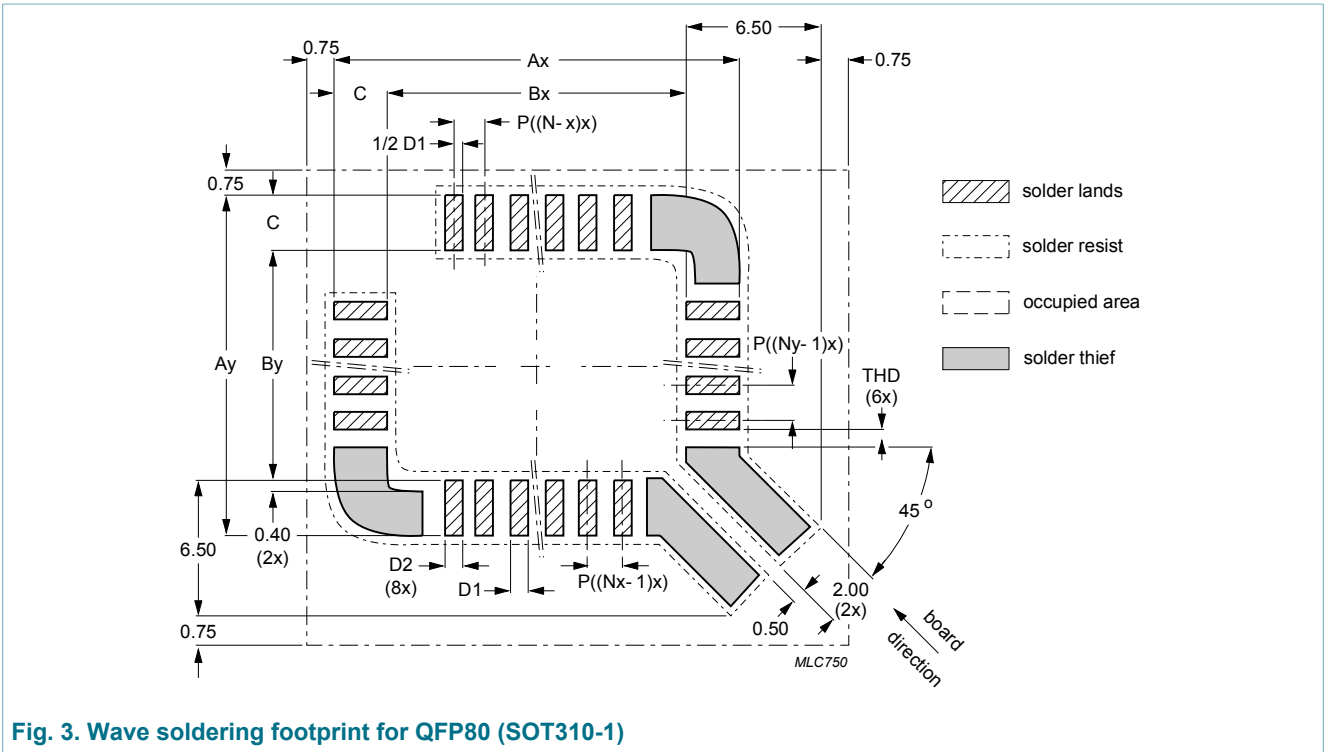


Fig. 2. Reflow soldering footprint for QFP80 (SOT310-1)

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4. Legal information

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5. Contents

1. Package summary.....	1
2. Package outline.....	2
3. Soldering.....	3
4. Legal information.....	5

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